Ultra High Performance BGA Cooling Solutions w/ Thermal Tape Attachment*

DIGI-KEY PART # ATS1144-ND

ATS PART # ATS-52400P-C2-R0

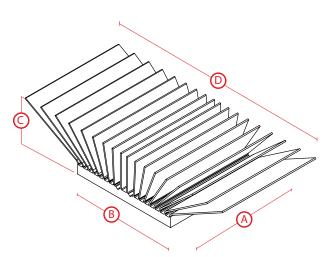
Features & Benefits

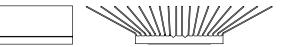
maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

Fabricated from extruded aluminum, which minimizes thermal resistance from the base to the fins, reduces weight and keeps costs low

Thermal Performance Table

Higher performance helps ensure reliable product life at a lower cost than other extruded heat sinks





AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED)	°C/W (DUCTED)	
200	1.0	2	1.6	
300	1.5	1.6		
400	2.0	1.4		
500	2.5	1.2		
600	3.0	1.1		
700	3.5	1.1		
800	4.0	1		
800	4.0	1		

Product Details[†]

DIMENSION A	DIMENSION B	DIMENSION C [§]	DIMENSION D	TIM [≠]	FINISH
40	40	17.5	69.14	C675	BLUE-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

Dimensions A & B refer to component size
Dimension C = the height of the heat sink of

§ Dimension C = the height of the heat sink shown above and does not include the height of the attachment method



To place an order, please visit www.digikey.com